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TECHNOLOGY CENTER 2800

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PATENT APPLICATION

RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2882

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiro MURATA

Group Art Unit: 2882

Application No.: 09/834,614 ✓

Examiner: G. WANG

Filed: April 16, 2001 ✓

Docket No.: 109278

For: THREE-DIMENSIONAL MOUNTED ~~ASSEMBLY~~ AND OPTICAL TRANSMISSION
DEVICE (AS AMENDED)

REQUEST FOR RECONSIDERATION AFTER FINAL REJECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the May 5, 2003 Office Action, reconsideration based on the following comments is respectfully requested.

Claims 1-21 are pending. Claims 1-10 are withdrawn from consideration.

I. The Claims Define Allowable Subject Matter

The Office Action rejects claims 11-12 and 17-21 under 35 U.S.C. §103(a) as unpatentable over U.S. Patent No. 5,522,002 to Chun in view of U.S. Patent No. 5,337,388 to Jacobowitz et al. This rejection is respectfully traversed.

Neither Chun nor Jacobowitz, nor their combination, teach, disclose or suggest the interconnections having a first exposed surface level with a first side of the molded body wherein the interconnections have a second exposed surface level with a second side of the molded body differing from the first side, as claimed in claim 11. Additionally, the applied

art does not disclose an interconnection having an exposed surface formed by a mold by which a side of a molded body is formed, as claimed in claim 21.

The Examiner asserts that Figure 2, reference 216 is the molded body of Chun and is exposed on many sides. Further, the interconnection (reference 250) is connected on an exposed surface level to that of the molded body in that area of the molded body. An interconnection (reference 223) is connected on an exposed surface level to that of the molded body in that area of the molded body. Applicant respectfully disagrees with the Examiner's position.

Specifically, Figure 2 is an enlarged simplified perspective view of an optical interconnect module, with a portion thereof removed (as shown by the cross-hatching). Reference 250 is a wire bond which allows the lead frame member 211 to be operably connected to the plurality of electrical traces 203. This connection enables input and output of electrical signals to enter and to exit the inner workings of the interconnect module 201 through electrical leads 210. Additionally, reference 223 is a wire bond used to illustrate interconnection between contacts 205 and interconnect substrate 202.

As such, the applied art does not teach, disclose or even suggest having the interconnections with a first exposed surface level width a first side of the molded body and the interconnections having a second exposed surface level width a second side of the molded body differing from the first side. Again, Figure 2 of Chun illustrates a cross-sectional view of the molded body and the interconnections so that their cross-sections are level. However, Chun fails to disclose that an exposed surface of the molded body and a side of the interconnections are level.

Therefore, Applicant submits for at least the reasons discussed above, independent claims 11 and 21 define patentable subject matter. Further, the claims that depend from the independent claims are distinguishable over the applied art for at least the reasons discussed,

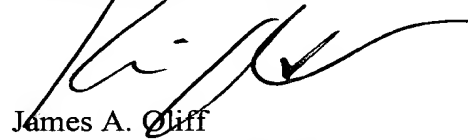
as well as for the additional features they recite. Withdrawal of the rejection of the claims under 35 U.S.C. §103 is respectfully requested.

II. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted,



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Date: July 31, 2003

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